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Part Number: [73656-5001](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)
[Product Specification PS-73670-9999 \(PDF\)](#)
[Application Specification AS-73656-1998 \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

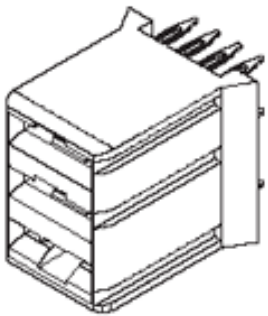
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73656](#)
Application Backplane
Comments Backplane Power Module
Component Type Power Header
Overview [HDM® Backplane Connector System](#)
Product Name HDM®
Style N/A
UPC 800756568225

Physical

Circuits (Loaded) 3
Circuits (maximum) 3
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Beryllium Copper
Material - Plating Mating Gold
Material - Plating Termination Tin-Lead
Material - Resin High Temperature Thermoplastic
Net Weight 1.640/g
Number of Columns 1
Number of Pairs Open Pin Field
Number of Rows 3
Orientation Vertical
PC Tail Length 3.50mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 2.36mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 0.889µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes



Series

image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Low-Halogen Status
Low-Halogen

China RoHS



Need more information on product environmental compliance?
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73656Series](#)

Mates With
[73651 HDM® Board-to-Board Daughterboard Power Module](#)

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
HDM Power Module Removal Tool	0621001100
Custom Power Module Insertion Tool	0622010100

Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	500V AC

Material Info

Reference - Drawing Numbers

Application Specification	AS-73656-1998
Product Specification	PS-73670-9999
Sales Drawing	SDA-73656-*00*

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This document was generated on 12/09/2014

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